

FOR IMMEDIATE RELEASE

Vicor Announces V•I Chip™ Through-Hole Packaging Option

Andover, MA, May 24, 2007...Vicor Corporation (NASDAQ: VICR) announced the immediate availability of a through-hole packaging option for all V•I Chips including MIL-COTS. This is in addition to existing surface mount (SMT) compatible packaging, doubling the available range.

Through-hole products are electrically and thermally identical to the SMT versions and are compatible with both hand soldering and wave solder techniques so they are perfect for fast prototyping or large production runs. Through-hole assembly facilitates multi-chip cold-plate or heatsink mounting, making system assembly simpler, faster and cheaper.

"The new through-hole packaging option is compatible with both leaded and lead-free solder," said Stephen Oliver, Vice President of Marketing and Sales. "For the MIL-COTS market, this option aligns with the Vicor MIL-STD MFIAM filters for a complete solution. Now, power designers in a broader range of applications can take advantage of the benefits of V•I Chips."

Information on board layout and 3D models is available. To access this information as well as data sheets for V•I Chip products, application notes and demo board user guides, please visit www.vicorpower.com.

To order through-hole V•I Chips, please contact Vicor Customer Service at 800-735-6200 or e-mail custserv@vicr.com.

Vicor Corporation designs, develops, manufactures, and markets modular power components and complete power systems used primarily by original equipment manufacturers (OEMs) in the communications, data processing, industrial control, test equipment, medical, and defense electronics markets.

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